

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
40V	8.5m $\Omega$ @10V	45A
	11m $\Omega$ @4.5V	

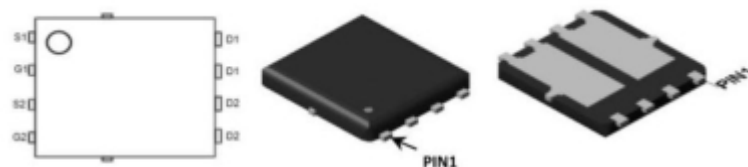
## Feature

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- 100% EAS tested

## Application

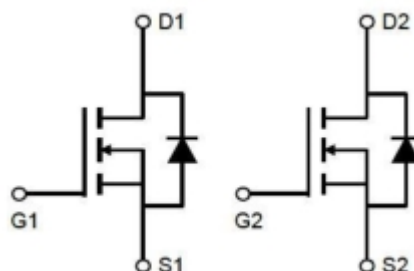
- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

## Package

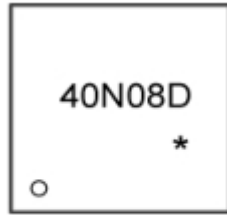


PDFNWB5X6-8L

## Circuit diagram



## Marking



40N08D : Product code  
\* : Month code.

## Absolute maximum ratings

(T<sub>a</sub>=25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	40	V
Gate-Source Voltage		V <sub>GS</sub>	20	V
Continuous Drain Current (Note 4)	T <sub>C</sub> =25°C	I <sub>D</sub>	45	A
Pulsed Drain Current <sup>(Note 1)</sup>	T <sub>C</sub> =25°C	I <sub>DM</sub>	180	A
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	83.8	W
Single Pulse Avalanche Energy <sup>(Note 6)</sup>		E <sub>AS</sub>	72	
Typical Thermal Resistance (Note 4,5)	Junction to Case	R <sub>θJC</sub>	1.79	°C/W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	°C

## Electrical characteristics

(T<sub>A</sub>=25°C, unless otherwise noted)

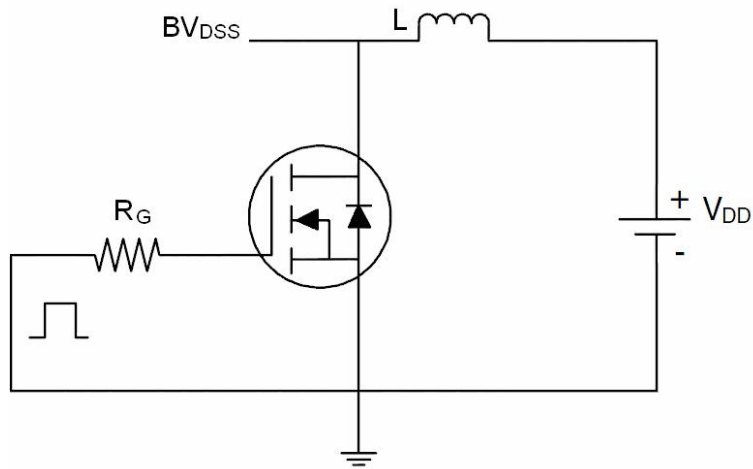
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV (BR) <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	40			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.5	2.5	V
Drain-Source On-State Resistance <sup>3</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =12A		8.5	11	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A		11	15	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V,V <sub>GS</sub> = 0V			1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V			±100	uA
Dynamic Characteristics <sup>(4)</sup>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V <sup>(Note 2,3)</sup>		22		pF
Gate-Source Charge	Q <sub>gs</sub>			4.2		
Gate-Drain Charge	Q <sub>gd</sub>			4		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		1013		pF
Output Capacitance	C <sub>oss</sub>			134		
Reverse Transfer Capacitance	C <sub>rss</sub>			88		
Switching Characteristics <sup>(4)</sup>						
Turn-On Delay Time	T <sub>d(on)</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3A <sup>(Note 2,3)</sup>		13		nS
Rise Time	T <sub>r</sub>			14		
Turn-Off Delay Time	T <sub>d(off)</sub>			45		
Fall Time	T <sub>f</sub>			9		
Diode Characteristics						
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				50	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A		0.7	1	V

### Notes:

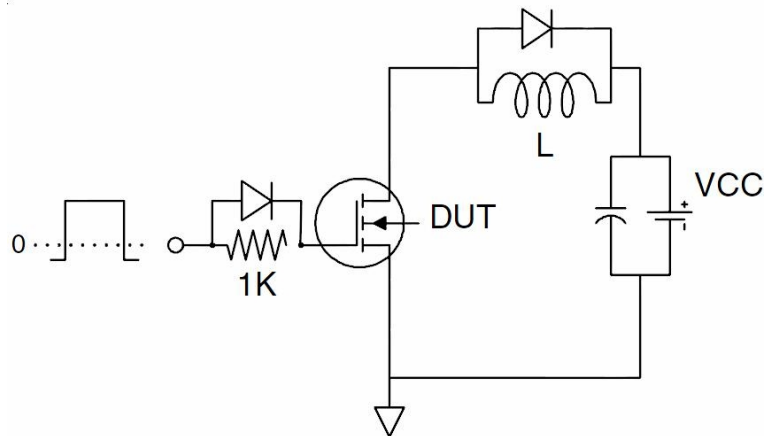
- Pulse width < 300μs, Duty cycle < 2%.
- Repetitive rating, pulse width limited by junction temperature T<sub>J</sub>(MAX) = 150°C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub> = 25°C.
- The maximum current rating is package limited.
- R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz. square pad of copper.
- The test condition is L = 0.1mH, V<sub>DD</sub> = 25V, V<sub>GS</sub> = 10V, Starting T<sub>J</sub> = 25°C

## Test Circuits

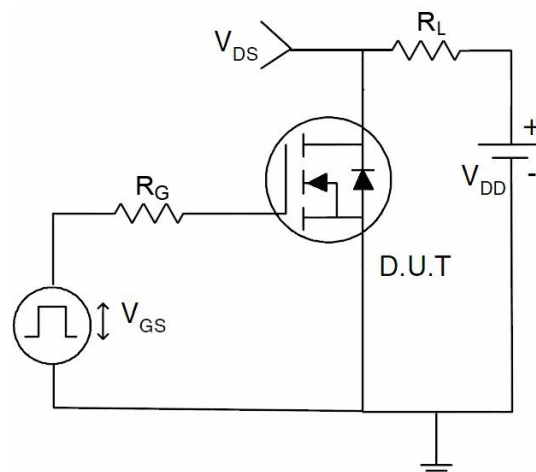
- EAS Test Circuits



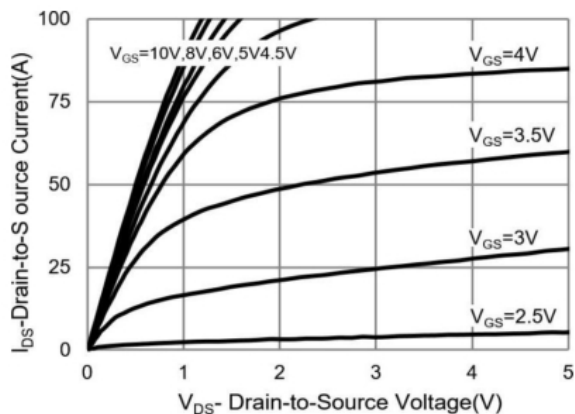
- Gate Charge Test Circuit



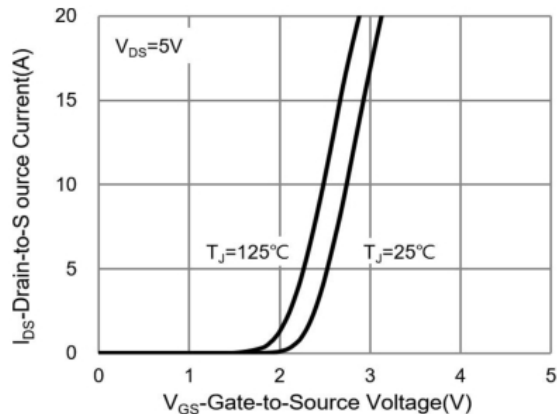
- Switch Time Test Circuit



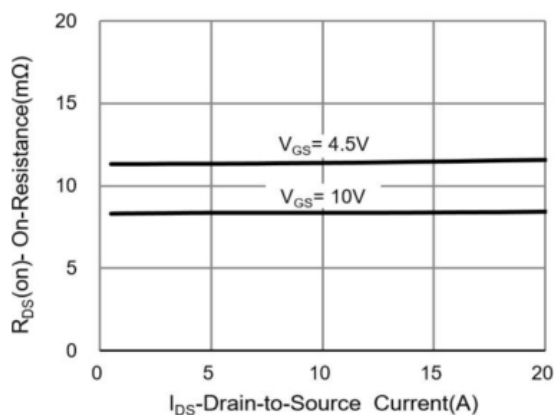
## Typical Characteristics



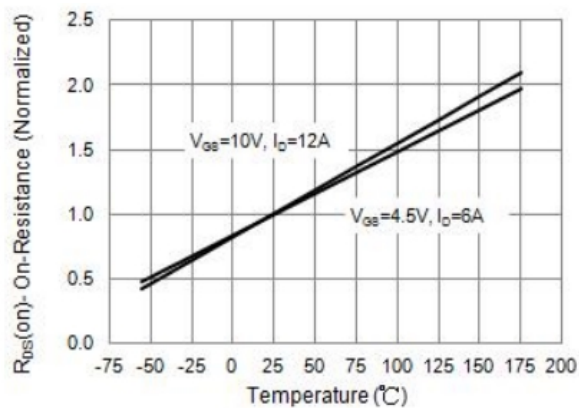
On-Region Characteristics



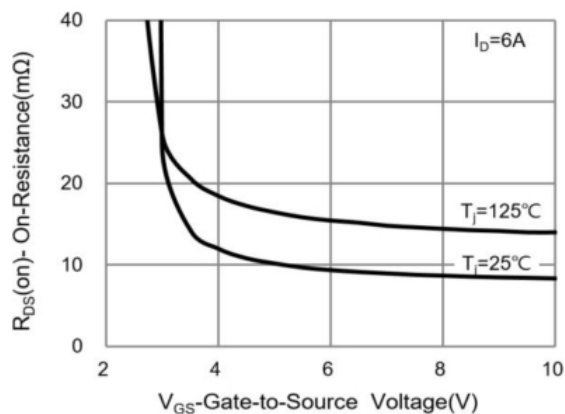
Transfer Characteristics



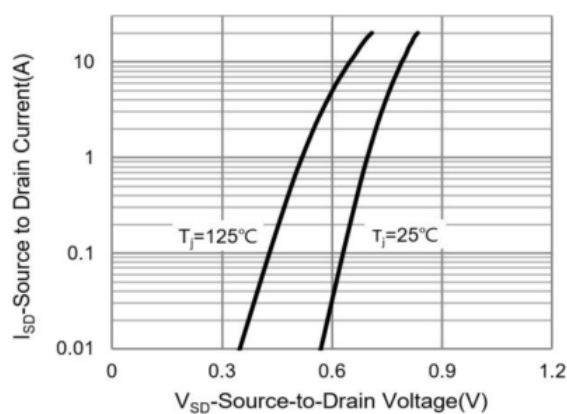
On-Resistance vs. Drain Current



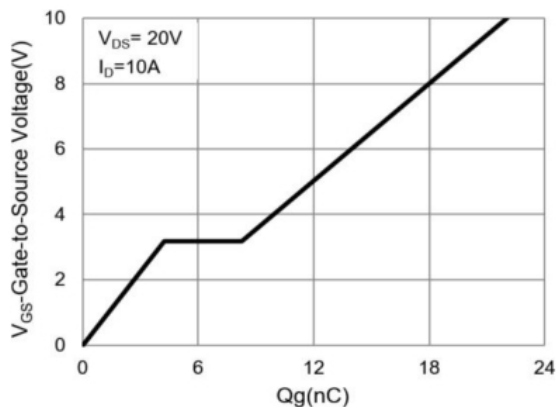
On-Resistance vs. Junction temperature



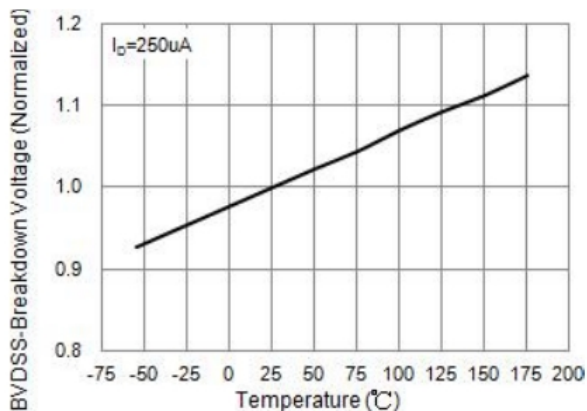
On-Resistance Variation with  $V_{GS}$



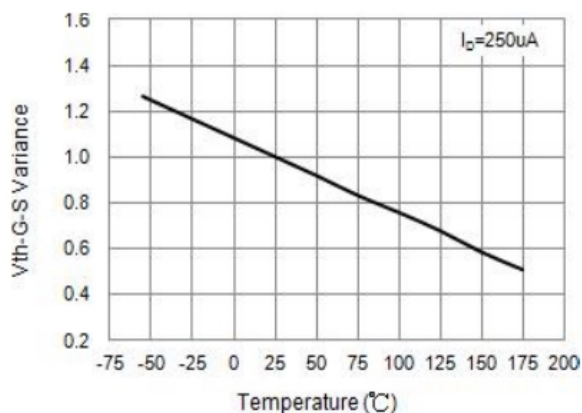
Body Diode Characteristics



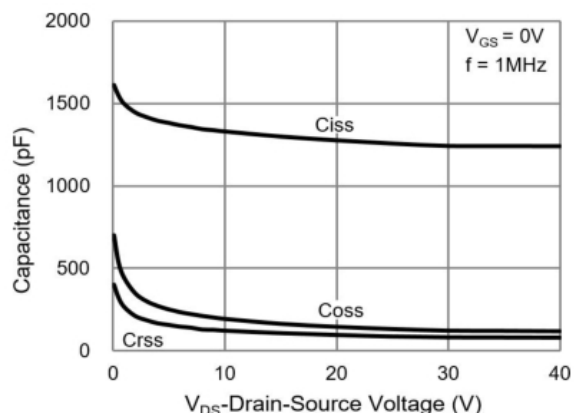
Gate-Charge Characteristics



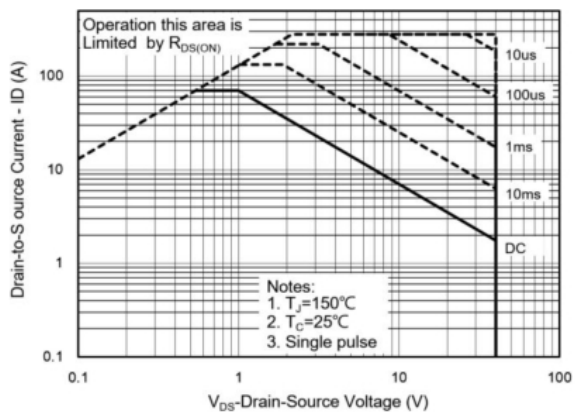
Breakdown Voltage Variation vs. Temperature



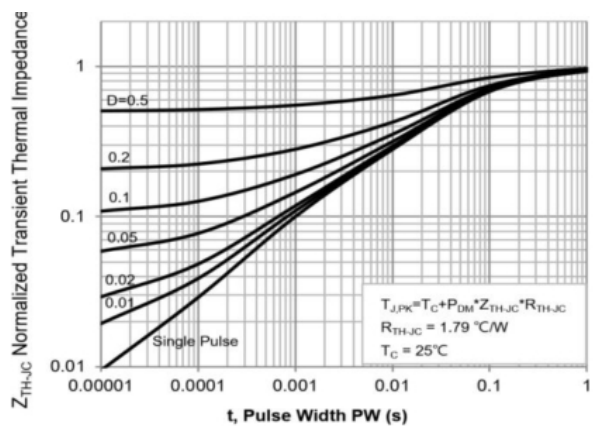
Threshold Voltage Variation with Temperature



Capacitance vs. Drain-Source Voltage

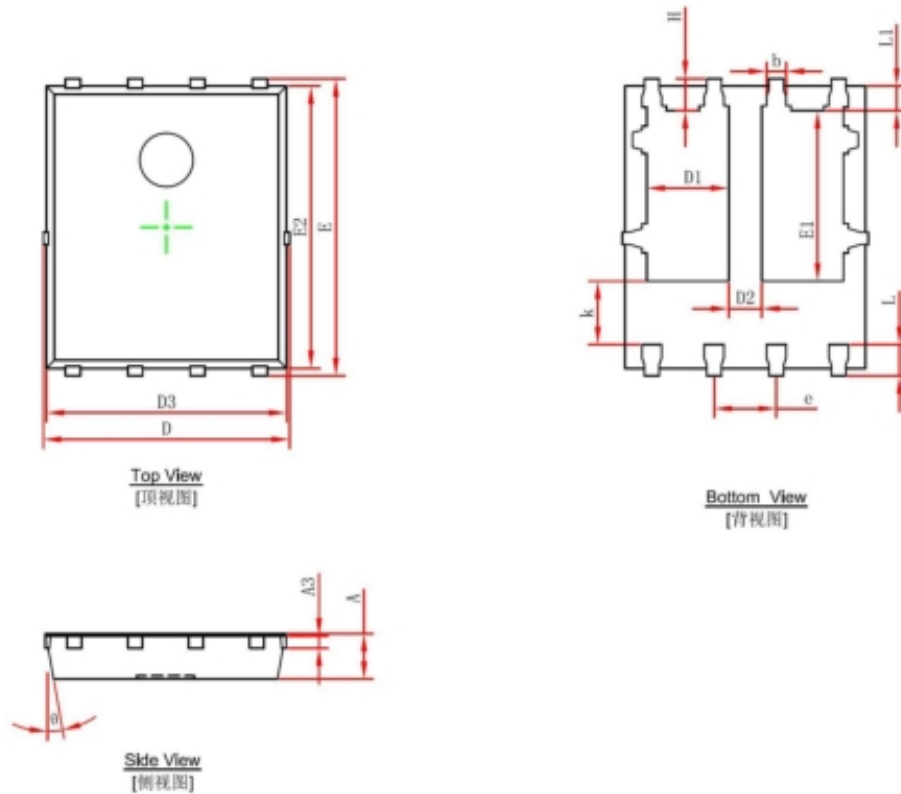


Maximum Safe Operating Area



Normalized Transient Thermal Impedance

## PDFNWB5X6-8L-A Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254 REF.		0.010 REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270 TYP.		0.050 TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°